



- NOTES
1. PACKAGE SHALL BE SELECTIVELY GOLD PLATED 60 μ INCHES MIN ON DIE ATTACH PAD AND WIRE BONDING FINGERS BYER NICKEL UNDERPLATING 40 μ INCHES MIN.
 2. OPTIONAL SELECTIVE NICKEL UNDERPLATING:
 OPTION-1: FULL NICKEL UNDERPLATING ON ALL EXPOSED METAL AND METALLIZED SURFACES PER NOTE 1.
 OPTION-2: SELECTIVE NICKEL UNDERPLATING ON DIE ATTACH PAD AND WIRE BONDING FINGERS ONLY PER NOTE 1.
 UNLESS SPECIFIED IN PURCHASE ORDER OPTION 1 SHALL BE APPLIED.
 3. LEAD RESISTANCE: 0.2 Ω MAX.

CHANGE _____ DATE _____ DRAWN _____ CHECKED _____ APPROVED _____				NAME 14 LEAD SIDE BRAZE PACKAGE	TOLERANCES UNLESS OTHERWISE SPECIFIED ±10% NLT. ±.005	DRAWN <i>P. Yamada</i>	CHECKED <i>J. Nakamura</i>
				SCALE 5 : 1	MATERIAL AS INDICATED	APPROVED _____	DATE JUN. 17, 90
				KYOTO CERAMIC CO., LTD.	KYOTO JAPAN	DWG. NO. KD-80285	